

1      **ABSTRACT OF THE DISCLOSURE**

2      The invention encompasses a board-on-chip package comprising an  
3      insulative substrate having circuitry thereon and an opening therethrough.  
4      A semiconductive-material-comprising die is adhered to the substrate and  
5      electrically connected to the circuitry with a plurality of electrical  
6      interconnects extending through the opening. A metal foil is in physical  
7      contact with at least a portion of the die. The invention also  
8      encompasses a method of forming a plurality of board-on-chip packages.  
9      An insulative substrate is provided. Such substrate has a repeating  
10     circuitry pattern thereon, and a plurality of openings therethrough. The  
11     openings are in a one-to-one correspondence with individual of the  
12     repeated circuitry patterns. A plurality of semiconductive-material-  
13     comprising dies are adhered to the substrate. Circuitry supported by the  
14     dies is electrically connected with the circuitry on the substrate utilizing  
15     a plurality of electrical interconnects extending through the openings.  
16     A metal foil is joined to the substrate and extended over the plurality  
17     of dies. The substrate and metal foil are cut to form singulated die  
18     packages comprising a single die, a portion of the substrate having a  
19     single repeated pattern of the circuitry, and a portion of the metal foil.

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